

1. General description

Enhanced ultrafast power diode in a TO252 (DPAK) plastic package.

2. Features and benefits

- High thermal cycling performance
- Soft recovery characteristic
- Low on-state losses
- Surface-mountable package
- Low thermal resistance
- Enhanced avalanche energy capability

3. Applications

- Dual Mode (DCM and CCM) PFC
- Power Factor Correction (PFC) for Interleaved Topology

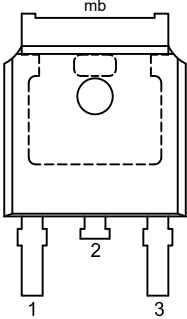
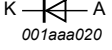
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
Absolute maximum rating						
V_{RRM}	repetitive peak reverse voltage		600			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 118$ °C; Fig. 1 ; Fig. 2 ; Fig. 3	10			A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25$ μ s; $T_{mb} \leq 118$ °C; square-wave pulse	20			A
I_{FSM}	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; Fig. 4	70			A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse;	80			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward voltage	$I_F = 10$ A; $T_j = 25$ °C; Fig. 6	-	1.5	2	V
		$I_F = 10$ A; $T_j = 150$ °C; Fig. 6	-	-	1.6	V
Dynamic characteristics						
t_{rr}	reverse recovery time	$I_F = 1$ A; $V_R = 30$ V; $di_F/dt = 50$ A/ μ s; $T_j = 25$ °C; Fig. 7	-	35	50	ns
		$I_F = 10$ A; $V_R = 200$ V; $di_F/dt = 200$ A/ μ s; $T_j = 25$ °C; Fig. 7	-	50	-	ns
		$I_F = 10$ A; $V_R = 200$ V; $di_F/dt = 200$ A/ μ s; $T_j = 125$ °C; Fig. 7	-	78	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected	 <p style="text-align: center;">DPAK (TO252N)</p>	
2	K	cathode[1]		
3	A	anode		
mb	mb	mounting base; connected to cathode		

[1] It is not possible to connect to pin 2 of the SOT428 package.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV10ED-600P	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	TO252N

7. Marking

Table 4. Marking codes

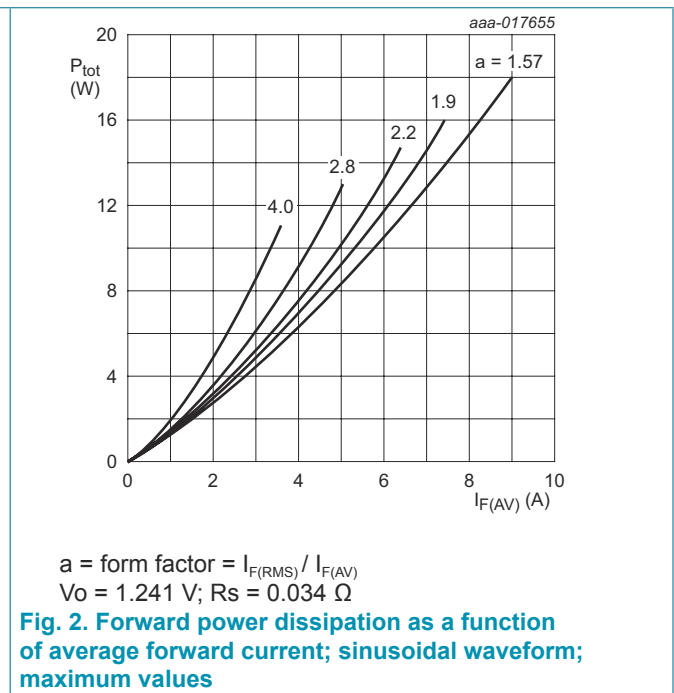
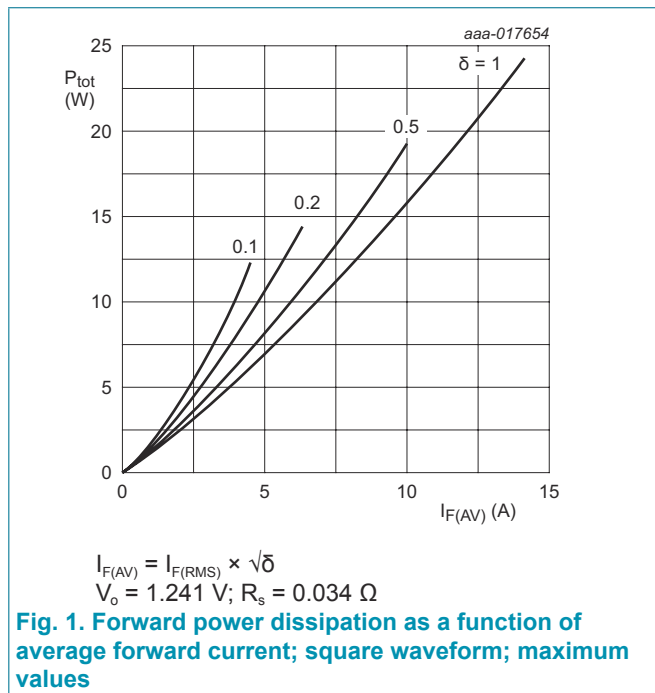
Type number	Marking code
BYV10ED-600P	BYV10ED-600P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 118\text{ }^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	10	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 118\text{ }^\circ\text{C}$; square-wave pulse	20	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse; Fig. 4	70	A
		$t_p = 8.3\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse;	80	A
T_{stg}	storage temperature		-40 to 175	$^\circ\text{C}$
T_j	junction temperature		175	$^\circ\text{C}$



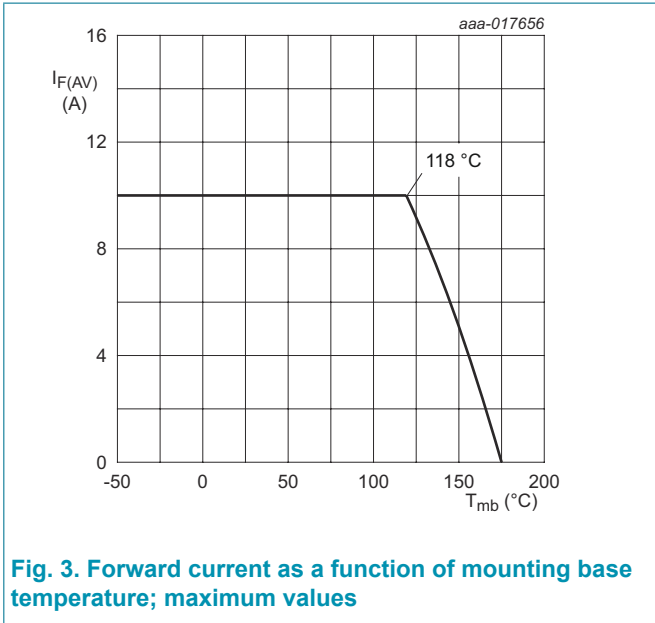


Fig. 3. Forward current as a function of mounting base temperature; maximum values

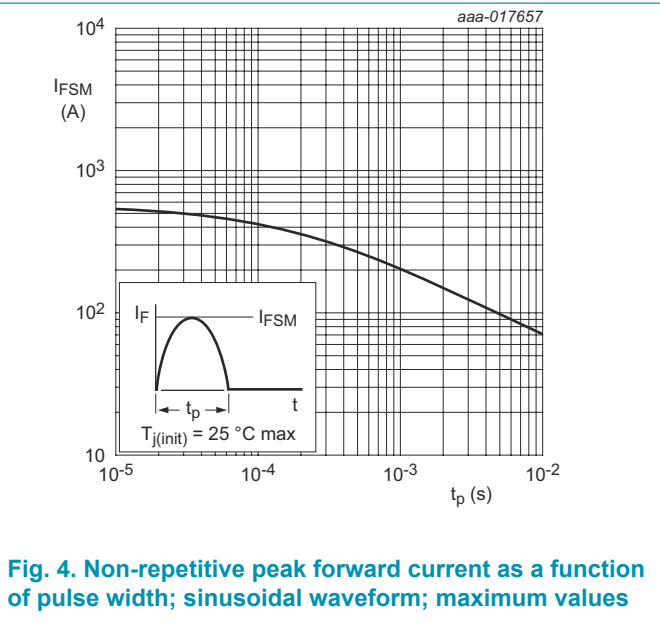
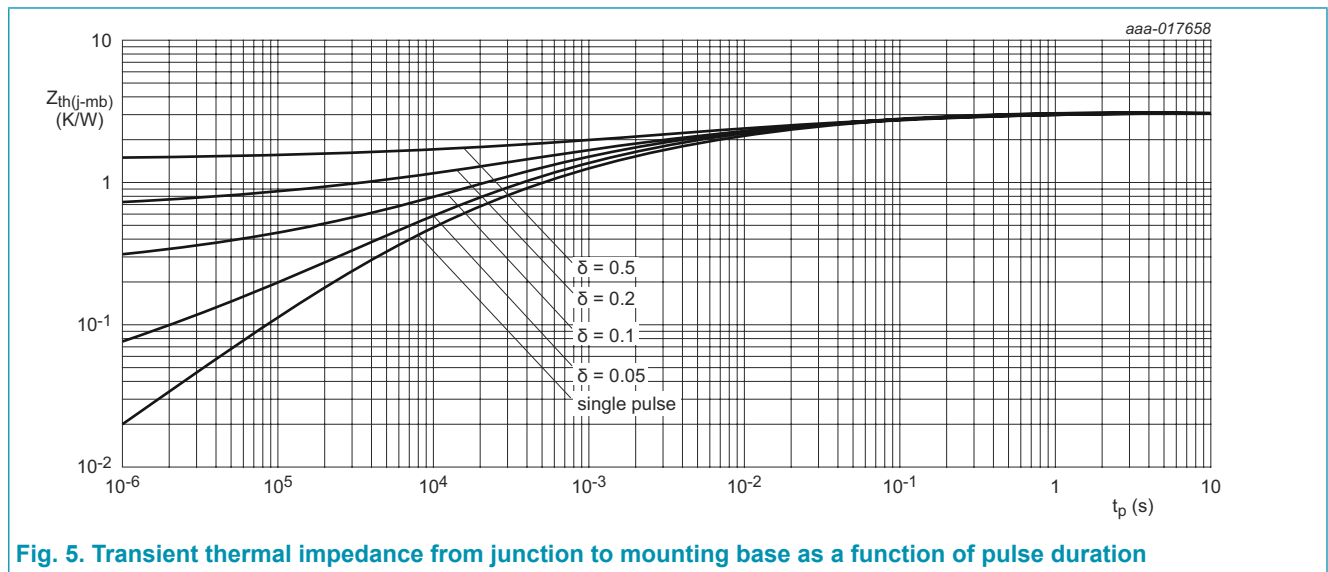


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

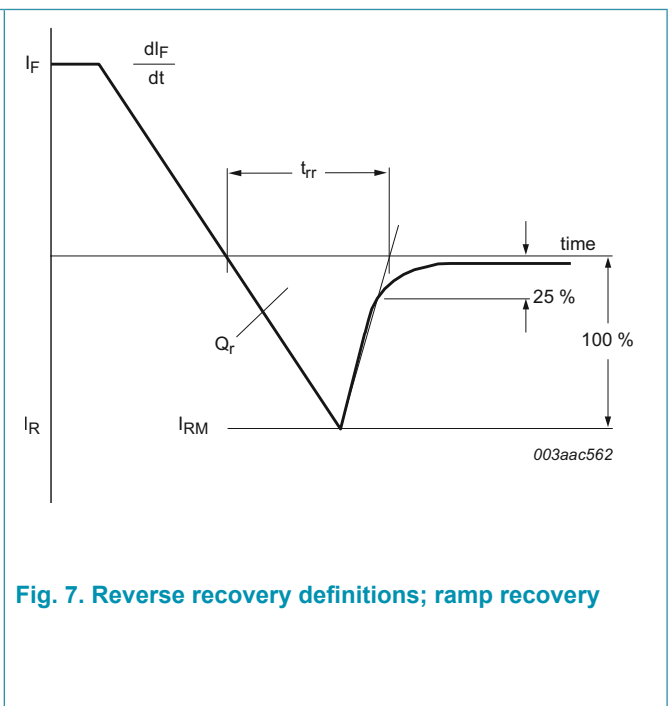
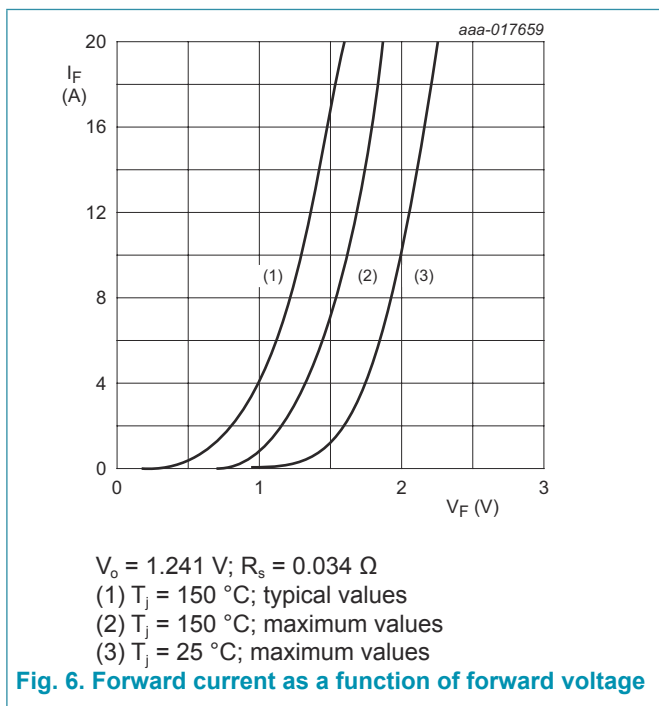
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	With heatsink compound; Fig. 5	-	-	3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	50	-	K/W



10. Characteristics

Table 7. Characteristics

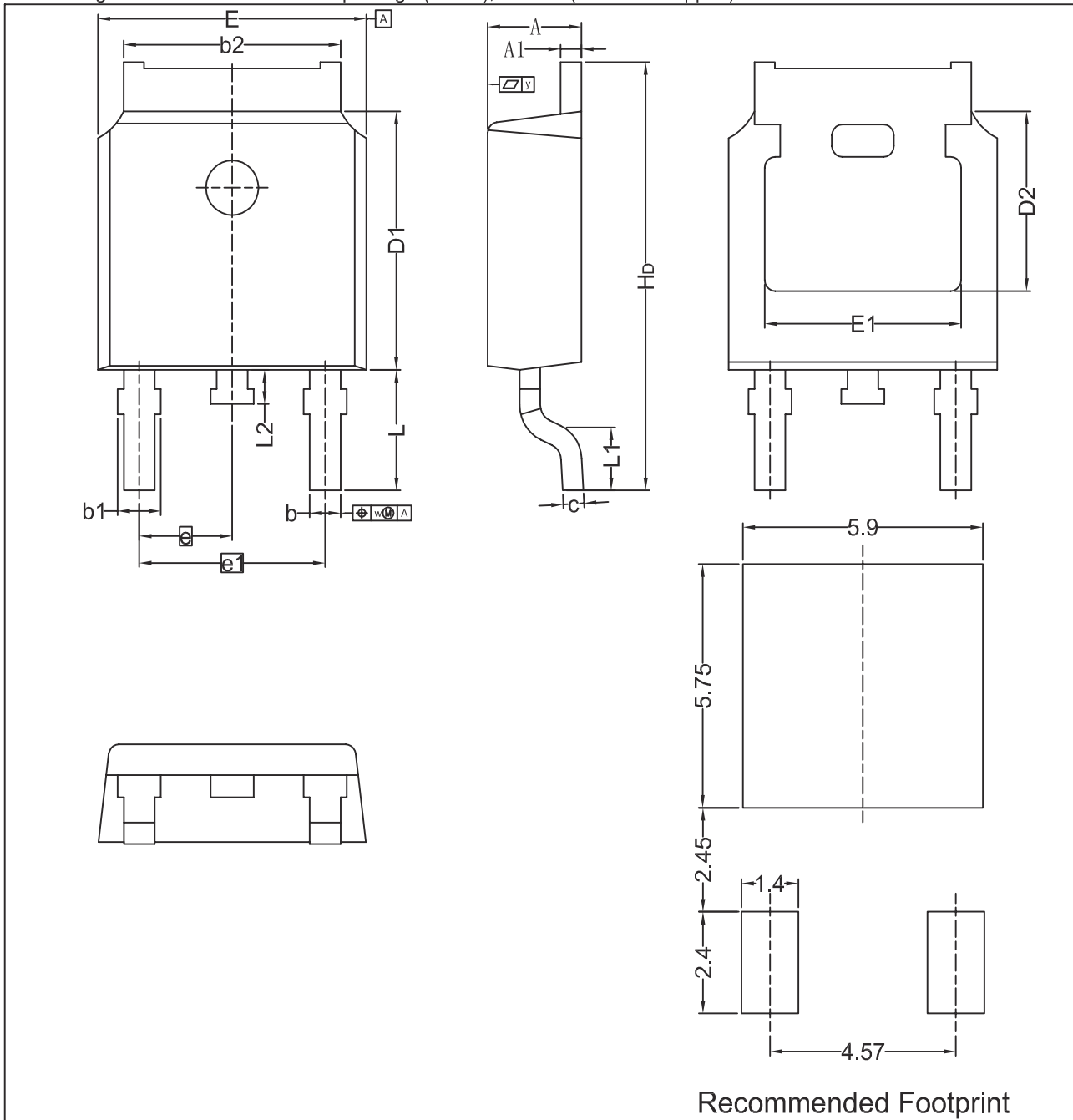
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward current	$I_F = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	1.5	2	V
		$I_F = 10 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	-	1.6	V
I_R	reverse current	$V_R = 600 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	10	μA
		$V_R = 600 \text{ V}; T_j = 150 \text{ }^\circ\text{C}$	-	-	500	μA
Dynamic characteristics						
Q_r	reverse charge	$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	123	-	nC
		$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	305	-	nC
t_{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	35	50	ns
		$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	50	-	ns
		$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	78	-	ns
I_{RM}	peak reverse recovery current	$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	4.9	-	A
		$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	7.8	-	A
E_{as}	non-repetitive avalanche energy	$I_R = 1.2 \text{ A}; T_{j(\text{init})} = 25 \text{ }^\circ\text{C}; L = 15 \text{ mH}$	10.8	-	-	mJ



11. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)

TO252



Recommended Footprint

Unit	A	A1	b	b1	b2	c	D1	D2	E	E1	e	e1	H _D	L	L1	L2	w	y
min	2.22	0.46	0.71	0.72	5.00	0.20	5.98	4.00	6.47	4.45	2.285	4.57	9.60	2.90 (Ref.)	0.50	0.50	0.20	0.20
mm nom																		
max	2.38	0.93	0.89	1.10	5.46	0.56	6.22	---	6.73	---			10.40	---	0.90			

Fig. 8. Package outline DPAK (TO252N)

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 4 July 2017
